



RW610FML: High-Performance Wi-Fi 6 and Bluetooth® Low Energy (LE) Combo Module with Integrated MCU

RW610FML NEW

Preproduction

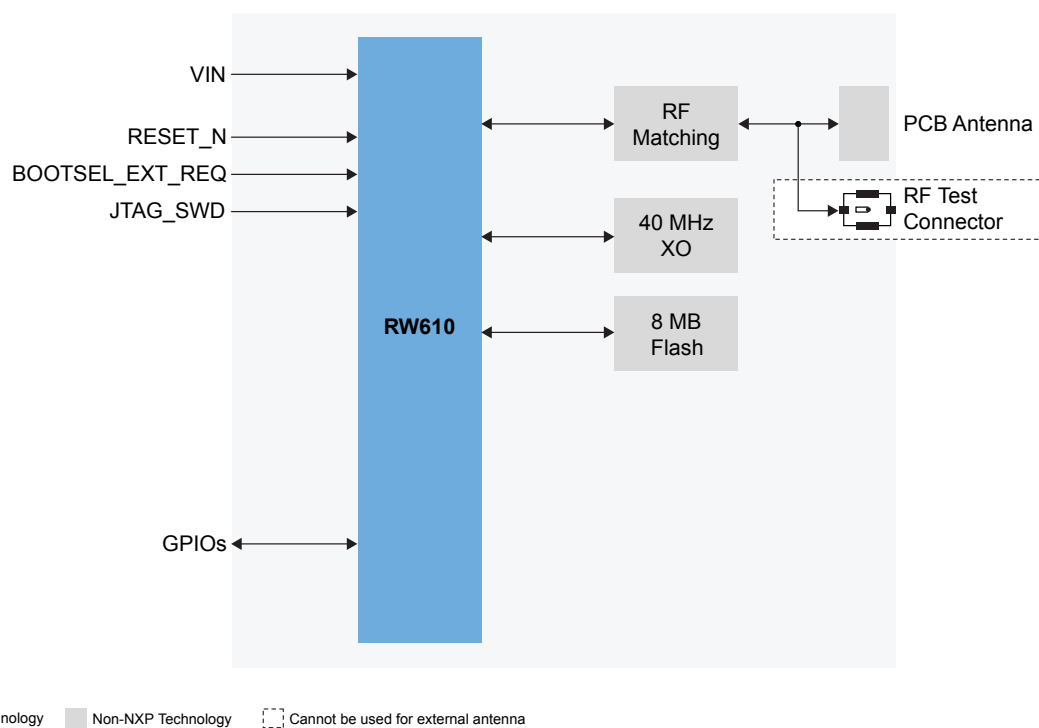
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The RW610FML is a low-power, high-performance Wi-Fi 6 and Bluetooth combo module supporting IEEE 802.11a/b/g/n/ac/ax and Bluetooth® Low Energy (BLE) protocols. The module integrates a rich set of peripheral interfaces, enabling flexible design and broad application support across IoT, and consumer devices.

RW610FML module is based on [RW610](#), a highly integrated, low-power wireless MCU with an integrated MCU and Wi-Fi® 6 + Bluetooth® Low Energy radios. The RW610 MCU subsystem includes a 260 MHz Arm® Cortex®-M33 core with Trustzone™-M, 1.2 MB on-chip SRAM and a high-bandwidth Quad SPI interface with an on-the-fly decryption engine for securely accessing off-chip execute-in-place (XIP) flash.

RW610FML Block Diagram



View additional information for [RW610FML: High-Performance Wi-Fi 6 and Bluetooth® Low Energy \(LE\) Combo Module with Integrated MCU](#).

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